



Atty. Dkt. No. AMAT/3577.X1/DSM/BCVD/JW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

AF/1700
16D
BK
1/6/03
(DE)

In re Application of:
Huang

Serial No.: 09/336,525

Confirmation No.: 7748

Filed: June 18, 1999

For: Plasma Treatment to Enhance
Adhesion and to Minimize
Oxidation of Carbon-Containing
Layers

Group Art Unit: 1762

Examiner: Padgett, M.

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Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>12/17/02</u> with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.	
Date <u>12/17/02</u>	Signature <u>Kint...</u>

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Dear Sir:

RESPONSE TO FINAL OFFICE ACTION DATED NOVEMBER 5, 2002

In response to the Final Office Action dated November 5, 2002, having a shortened statutory period for response set to expire on February 5, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below.

IN THE CLAIMS:

Please cancel claims 46-47 and 49, without prejudice. For the Examiner's convenience, all pending claims as set forth below and amendments are proposed as noted below.

24. (Amended) A method of processing a semiconductor substrate, comprising: